

## Reliability Engineering Report Summary Sheet

# 0.35um Process Technology Flash-MCU (Fujitsu Semiconductor Technology)

**Package Type: LQFP**

CD2008-3557A

FML Quality Assurance Division

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## Reliability Test

Device Type : MB91F376G  
 Package Type : Plastic LQFP-120 Package

Test Item	Test Condition	Tested Number		Tested Time	Failed Number
High Temperature Operation Life 高温連続動作試験	125 °C 6.0V CLK FREQ.= 500Hz	231 (77×3Lot)	(a)	1000h	0
Temperature Humidity Bias 高温連続動作試験	85 °C / 85% RH 6.0V CLK FREQ.= 500Hz	138 (46×3Lot)	(a)	1000h	0
High Temperature Storage 高温保存試験	150 °C	231 (77×3Lot)	(a)	1000h	0
Temperature Cycling 温度サイクル	-65°C~150°C	231 (77×3Lot)	(a)	200cyc	0
Pressure Cooker Test	121°C, 100%RH: 2.03E5 Pa	231 (77×3Lot)	(a)	168h	0
Pressure Cooker Test with Bias	130°C, 85%RH: 2.33E5 Pa 6.0V	99 (33×3Lot)	(a)	96h	0

(a) Pre-condition: Baking (125°C, 24h) +Moisture Absorption (30°C/80%RH, 72h) +IR 240°C Max.

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## Data Retention Test

Device Type : MB91F376G

Test Item	Test Condition	Number Tested	Tested Time	Number Failed
Data Retention Bake (WLB) (ウェーハレベル)	250 °C (Data pattern all'0')	231	168h	0

## Endurance Test

Device Type : MB91F376G

Package Type : LQFP-120

Test Item	Test Condition	Number Tested	Tested Time	Number Failed
Endurance Test 書き換え試験	125 °C, 5.5 V	231	10,000 times	0

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